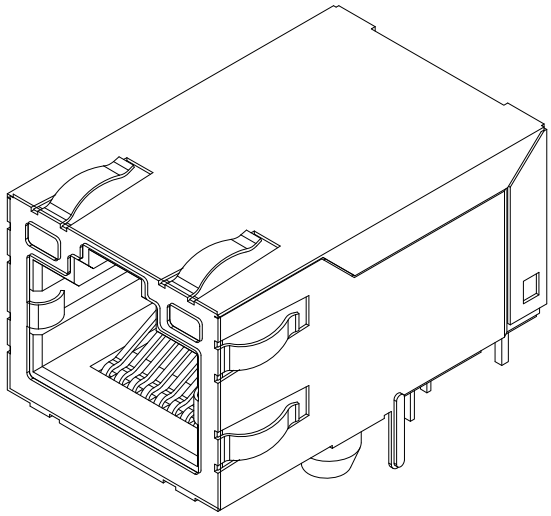
PRODUCT SPECIFICATION



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REVISION:	ECR/ECN INFORMATION:		PRODUCT NO	KHGDIXR-883-BEx	SHEET No
A	EC No: DATE:	2009/11/03	PRODUCT NAME	MODULAR JACK RIGHT ANGLE WITH INTEGRATED MAGNETICS	1 of 7

DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-GD-0002	JEFF.YANG	DAVID.CHEN	TONY.CHANG

1.0 SCOPE

This Product Specification covers the Modular Jack Right Angle Dip With Integrated Magnetics with selective gold and tin plating for IR reflow application

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

Modular Jack Right Angle With Integrated Magnetics

PRODUCT NUMBER(S)

PRODUCT NAME	SERIES NUMBER
HTGDIXR-883-BE-ISI50170-G/Y-T3	KHGDIXR-883-BE1
HTGDIXR-883-BE-ISI50170-G/G-01	KHGDIXR-883-BE3
HTGDIXR-883-BE-ISI50152-T3 (FOR 4KV)	KHGDIXR-883-BE5
HTGDIXR-883-BE-ISI50170-G/G-T3	KHGDIXR-883-BE6
HTGDIXR-883-BE-ISI50170-G/Y-E3	KHGDIXR-883-BE7
HTGDIXR-883-BE-PJ1035-G/Y-T3	KHGDIXR-883-BE8
HTGDIXR-883-BE-ISI50170-G/G	KHGDIXR-883-BE9
HTGDIXR-883-BA-ISI50170	KHGDIXR-883-BA10

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate sales drawings (SD-48025-007,009,010,011,012) for information on dimensions, materials, plating and markings.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

FCC Rules and Regulations, PART 68, Subpart F
REA Bulletin 345-81, PE-76; Specification for modular telephone set hardware
ANSI/EIA/TIA-568
IEC-60603-7
UL 1863
MIL-STD-202; General requirements for test specifications

4.0 RATINGS OF CONNECTOR

4.1 VOLTAGE

150 V $_{RMS}$ AC (Ringing voltage only)

4.2 CURRENT

1.5 AMPS @ 25°C

4.3 TEMPERATURE

Operating**:** - 40°C TO + 70°C

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	**DC Resistance**	Apply a maximum voltage of **20** mV and a current of **100** mA. (Measure J6-J3 or J2-J1)	**1.2** Ω MAXIMUM
2	**Insulation Resistance**	Unmated connector, mounted to a PCB: apply a voltage of **100** VDC between adjacent terminals and between terminals to ground.	**500** Megohms MINIMUM
3	**Current Temperature Rating**	Mate connector, and measure the temperature at the rated current **(1.5Amps)** after **1** hour	**30**℃ rise MAXIMUM from initial.
4	**Dielectric Withstanding Voltage**	**1500** VAC rms (**1**mA cutoff current) for **60** seconds.	No Breakdown

5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	**Connector Mate Force**	Mate connector at a rate of **25 ± 6** mm (**1 ± ¼** inch) per minute.	**22** N (**5** lbf) unshielded MAXIMUM insertion force **35** N (**8** lbf) shielded MAXIMUM insertion force
6	**Durability**	Mate connectors up to **750** cycles at a maximum rate of **10** cycles per minute prior to Environmental Tests.	**1.2** Ω MAXIMUM
7	**Vibration (Random)**	Amplitude: 1.50mm (.060”) peak to peak Sweep: 10-55-10 Hz in one minute Duration: 15 minutes Direction: X, Y,Z axis (45 minutes total)	1.Discontinue ≦ 1microsecond 2. **1.2** Ω MAXIMUM
8	**Plug Retention Force**	Apply an axial pullout force on the plug at a rate of **25 ± 6** mm (**1 ± ¼** inch).	**89** N (**20** lbf) MINIMUM retention force
9	**Shock (Mechanical)**	Mate connectors and shock at **50 G** Half-sine,**11ms** form shocks in the X, Y, Z axis (9 shocks total).	1.Discontinue ≦ 1microsecond 2. **1.2** Ω MAXIMUM
10	**Solderability**	Dip solder tails into the molten solder (held at **245 ± 5**℃) up to 1.0mm from the bottom of the housing for **5 ± 1** second	Solderable area shall have minimum of **95**% solder coverage

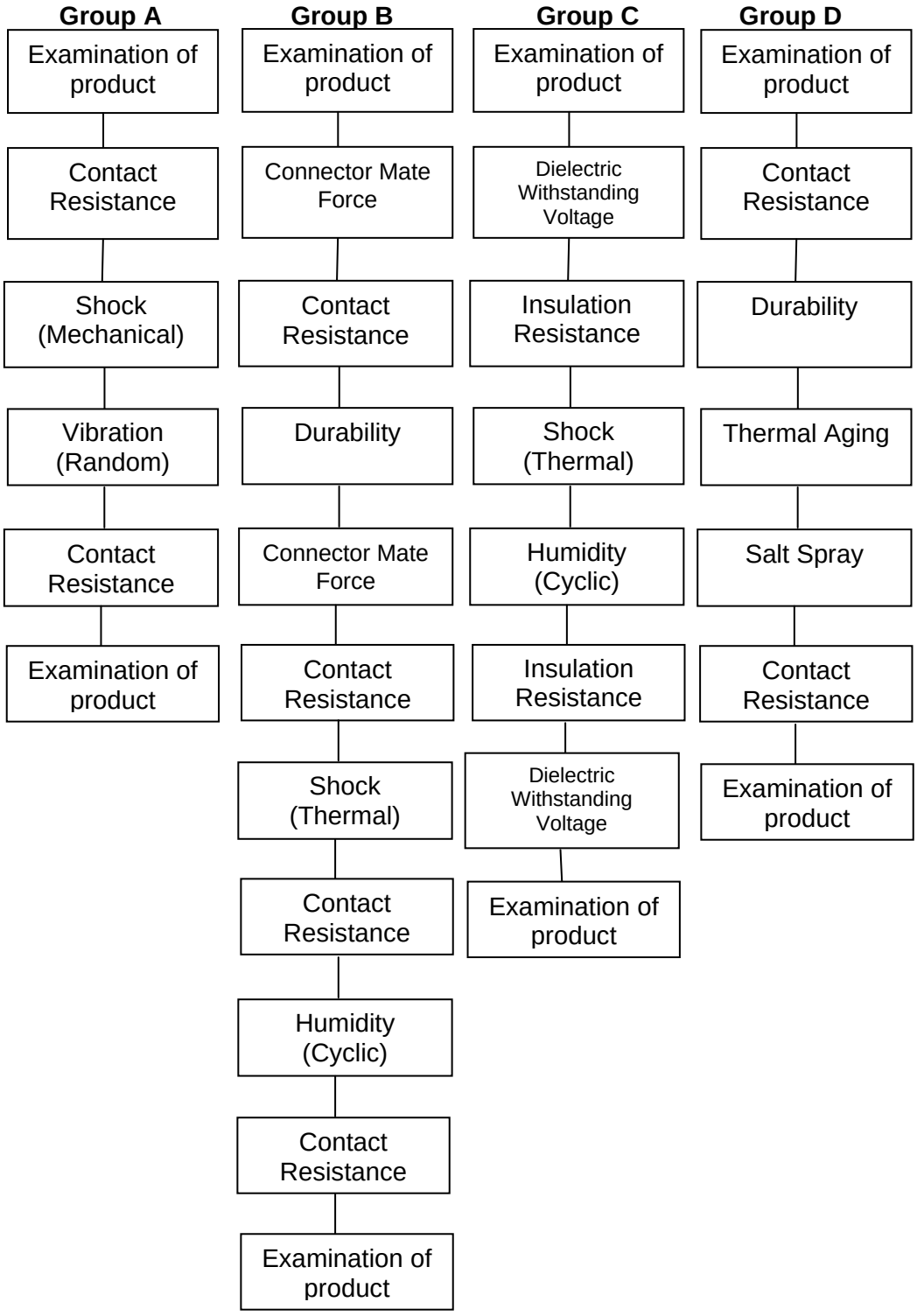
5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
11	**Shock (Thermal)**	Mate connectors; expose to **10** cycles of: **-40**°C to +**85**°C **30** minutes dwell	1.IEEE traffic test not to fail. 2. Visual: No Damage 3. **1.2** Ω MAXIMUM
12	**Thermal Aging**	Mate connectors; expose to: **48** hours at **85±2**°C	1.IEEE traffic test not to fail. 2. Visual: No Damage 3. **1.2** Ω MAXIMUM
13	**Humidity (Cyclic)**	Mate connectors: expose to **10** cycles at **90-95**% relative humidity with temperatures at +**25**°C and +**65**°C per MIL-STD-202F method 106F (without -10°C dip)	1.IEEE traffic test not to fail. 2. Visual: No Damage 3. **1.2** Ω MAXIMUM
14	**IR Reflow**	See appendix "A"	1.IEEE traffic test not to fail. 2.Visual: No Damage 3. LED function not to fail
15	**Salt Spray**	**5±1**% salt solution Duration **48** hrs	1.Visual: No Damage 2. LED function not to fail 3. **1.2** Ω MAXIMUM

Note:

All tests shall meet visual requirements, show no physical damage and meet requirements of following additional 5.4 tests group. The test group shows the test sequences and shall completely test 5 pcs samples in each group. There are another four test items (Current Temperature Rating, Plug Retention Force, Solderability, IR Reflow) should be done by individual test condition and requirement shown above.

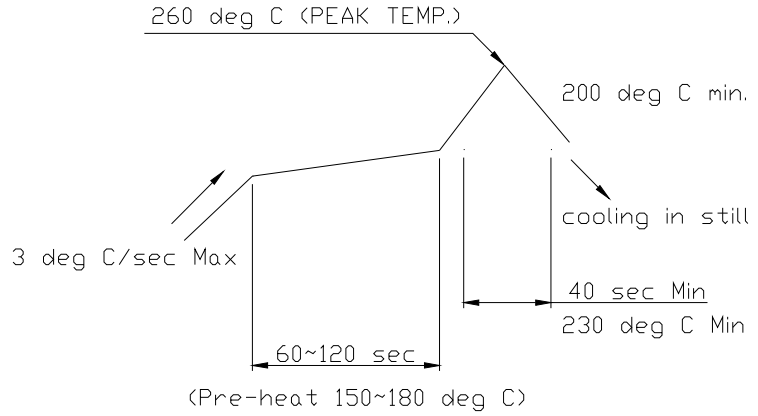
5.4 TEST GROUP / TEST SEQUENCE



5.5 APPENDIX "A" (Pls review with Rockwell spec.)

(INFRARED SOLDERING CONDITION)

TEMPERATURE CONDITION GRAPH
TEMPERATURE ON BOARD PATTERN SIDE
TWICE



(NOTE)

1.Pleose check the reflow soldering condition by your own devices beforehand
Because the condition changes by the soldering devices, P.C.Boards, and so on.

2. Thickness of the cream solder shall be maintained 0.12mm Min.
After reflow process.

6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage.
See appropriate sales drawings.

7.0 OTHER INFORMATION

(A) MAGNETICS ELECTRICAL PERFORMANCE & LED ELECTRICAL PERFORMANCE SEE APPROPRIATE SALES DRAWINGS

(B) Plug retention force test instruction